

L Number	Hits	Search Text	DB	Time stamp
1	435	(contact adj plug) and soi	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2004/09/01 13:33
2	390	(contact adj plug) and soi and metal	US-PGPUB; EPO; JPO; DERWENT;	2004/09/01 13:34
3	214	(contact adj plug) and soi and (metal adj (film or layer))	DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2004/09/01 15:21
5	34	(contact) with soi with (metal adj (film or layer))	US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2004/09/01 15:20
6	1056	(contact adj hole) and soi and (metal adj (film or layer))	US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2004/09/01 15:21
7	187	(contact adj via) and soi and (metal adj (film or layer))	US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2004/09/01 15:22
-	5	(soi adj layer) with substrate with (crystal adj direction)	US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2004/08/30 12:47
-	0	(soi adj film) with substrate with (crystal adj direction)	US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2004/08/30 12:47
-	7	(soi) with substrate with (crystal adj direction)	US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2004/08/30 12:50
-	46	(soi) with substrate with (crystal adj orientation)	US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2004/09/01 13:32